

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang  
Assignee: Bridge Semiconductor Corporation  
Title: METHOD OF MAKING A SEMICONDUCTOR PACKAGE  
DEVICE THAT INCLUDES A CONDUCTIVE TRACE WITH  
RECESSED AND NON-RECESSED PORTIONS  
Serial No.: 10/059,686 Filed: January 29, 2002  
Examiner: Zarneke, D. Group Art Unit: 2827  
Atty. Docket No.: BDG005-1


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COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313

TRANSMITTAL OF FORMAL DRAWINGS

Attached please find the formal drawings (29 sheets) for this application.

I hereby certify that this correspondence is being deposited with  
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Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA  
22313-1450, on December 15, 2003.

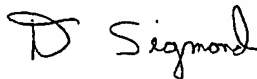


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12, 15, 03

Date of Signature

Respectfully submitted,



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